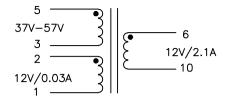


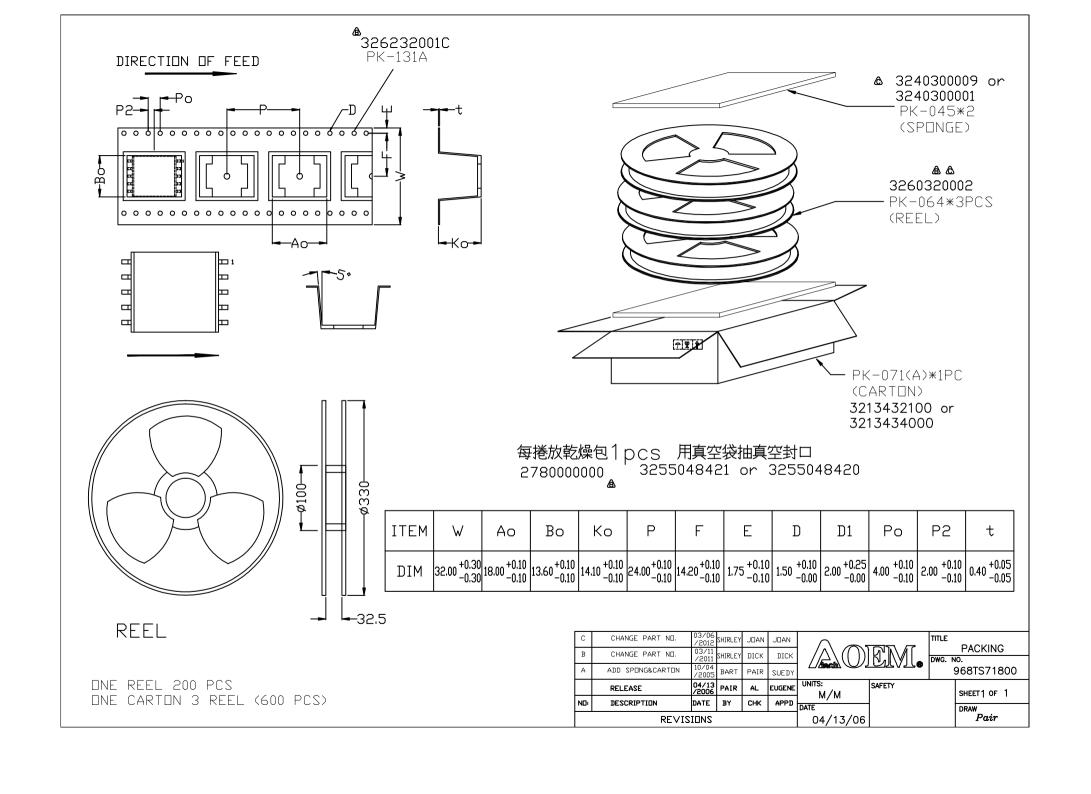
SUGGESTED P.C.B LAYOUT



ELECTRICAL CHARACTERISTICS:

- 1. DCR : PIN $5-3 = 89m\Omega$ MAX. PIN $6-10 = 28m\Omega$ MAX. PIN $2-1 = 96m\Omega$ MAX.
- 2. INDUCTANCE : (@250kHz, 0.1Vrms) PIN $5-3 = 37uH \pm 10\%$
- \triangle 3. LEAKAGE INDUCTANCE (@250kHz, 0.1Vrms) PIN 5-3 (PIN 1-2, 6-10 SHORT) = 0.75uH MAX.
 - 4. TURN RATIO : (@100kHz, 0.1Vrms) PIN 5-3 : $6-10 = 2 \pm 1\%$ PIN 5-3 : $2-1 = 2 \pm 1\%$
 - 5. HI-POT: (@1500VAC, 2mA, 2SEC): PIN 5-6
 - 6. RoHS COMPLIANT

						\(\)		TITLE	FLYBACK
								DWG. N	TRANSFORMER D.
A	CHANGE LEAKAGE INDUCTANCE	12/13 /2016	SHIRLEY	BETTY	BETTY				ATS-1252R
	RELEASE	07/05 /2013	SHIRLEY	BETTY	BETTY	UNITS: M/M	SAFETY		SHEET 1 OF 1
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE	P/N:		DRAW
	REVI			07/05/2013	l '		SHIRLEY		





Pb-free Soldering IR Reflow(SMD)



1,MSL Grade: 1 Level 2,Floor life: 2years 3,Condition:≤30°C RH 85% 2,Form-1(Reference JEDEC J-STD-020D Table 5-2)

	IR reflow profile	Pb-free	
step#	Profile Feature	Condition/Duration	
step1	Ramp-up rate	3°C/second max	
step2	Preheat:150°C-200°C(Ta-Tb)	t1-t2:60-120seconds	
step3	Ramp-up rate(TL to Tp)	3°C/second max	
sieps	Temperature maintained above 217°C	60-150seconds	
ston/	Peak temperature(Tp)	260+0/-5℃	
step4	Time within 5°C of actual peak temperature	30seconds max	
	Ramp-down rate(Tp to TL)	6°C/second max	

3,Form-2(Reference JEDEC J-STD-020D Table 4-2)

Package	Volume mm ³	Volume mm ³	Volume mm ³ >2000	
Thickness	<350	350-2000		
<1.6mm	260+0/-5°C	260+0/-5°C	260+0/-5℃	
1.6mm-2.5mm	260+0/-5°C	250+0/-5°C	245+0/-5℃	
>2.5mm	250+0/-5° C	245+0/-5°C	245+0/-5℃	